



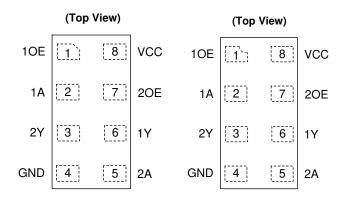
74LVC2G126

DUAL BUFFER GATE WITH 3-STATE OUTPUTS

Description

The 74LVC2G126 is a dual buffer gate with 3-state outputs. The device is designed for operation over a power supply range of 1.65V to 5.5V. The device is fully specified for partial power down applications using $I_{\rm OFF}$. The $I_{\rm OFF}$ circuitry disables the output, preventing damaging current backflow when the device is powered down.

Pin Assignments



X2-DFN1210-8

X2-DFN1410-8/X2-DFN2010-8

January 2020

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Features

- Wide Supply Voltage Range from 1.65 to 5.5V
- ±24mA Output Drive at 3.3V
- CMOS Low Power Consumption
- I_{OFF} Supports Partial-Power-Down Mode Operation
- Inputs accept up to 5.5V
- Schmitt Trigger Action at all inputs makes the circuit tolerant for slower input rise and fall times. The hysteresis is typically 100mV at V_{CC} = 3.0V.
- ESD Protection Exceeds JESD 22
 - 2000-V Human Body Model (A114)
 - Exceeds 1000-V Charged Device Model (C101)
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.

https://www.diodes.com/quality/product-definitions/

Applications

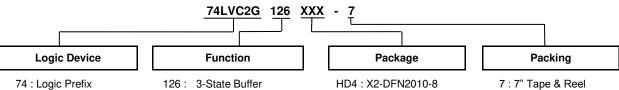
- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide Array of Products Such as:
 - PCs, Networking, Notebooks, Netbooks, PDAs
 - Tablet Computers, E-Readers
 - Computer Peripherals, Hard Drives, CD/DVD ROMs
 - TVs, DVDs, DVRs, Set Top Boxes
 - Cell Phones, Personal Navigation / GPS
 - MP3 Players, Cameras, Video Recorders

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



Ordering Information (Note 4)



74 : Logic Prefix LVC: 1.65V to 5.5V Logic Family 2G: Dual Gate

HD4: X2-DFN2010-8 HK3: X2-DFN1410-8

RA3: X2-DFN1210-8

	Package Package Package		7" Tape and Re	el (Note 6)	
Device	Code	(Note 5)	Size	Quantity	Part Number Suffix
74LVC2G126HD4-7	HD4	X2-DFN2010-8	1.95mm × 1.0mm × 0.4mm 0.5mm Lead Pitch	5,000/Tape & Reel	-7
74LVC2G126HK3-7	HK3	X2-DFN1410-8	1.35mm × 1.0mm × 0.35mm 0.4mm Lead Pitch	5,000/Tape & Reel	-7
74LVC2G126RA3-7	RA3	X2-DFN1210-8	1.2mm × 1.0mm × 0.35mm 0.3mm Lead Pitch	5,000/Tape & Reel	-7

Notes:

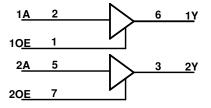
OE - High

For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.
 Pad layout as shown in Diodes Incorporated's package outline PDFs, which can be found on our website at http://www.diodes.com/package-outlines.html.
 The taping orientation is located on our website at https://www.diodes.com/assets/Packaging-Support-Docs/Ap02007.pdf.

Pin Descriptions

Pin Name	Pin Number	Description	
10E	1	Output Enable for buffer 1	
1A	2	Data Input	
2Y	3	Data Output	
GND	4	Ground	
2A	5	Data Input	
1Y	6	Data Output	
20E	7	Output Enable for buffer 2	
VCC	8	Supply Voltage	

Logic Diagram



Function Table

Inp	Output	
OE	Α	Υ
Н	Н	Н
Н	L	L
L	X	Z



Absolute Maximum Ratings (Notes 7 & 8)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
Vcc	Supply Voltage	-0.5 to +6.5	V
Vı	Input Voltage	-0.5 to +6.5	V
Va	Output Voltage - Active Mode	-0.5 to V _{CC} +0.5	V
Vo	Output Voltage Power Down Mode	-0.5 to +6.5	V
lık	Input Clamp Current VI < 0	-50	mA
lok	Output Clamp Current (Vo < 0 or Vo > Vcc)	±50	mA
lo	Continuous Output Current (V _O = 0 to V _{CC})	±50	mA
Icc	Continuous Current Through Vcc	100	mA
Ignd	Continuous Current Through GND	-100	mA
TJ	Operating Junction Temperature	-40 to +150	°C
Tstg	Storage Temperature	-65 to +150	°C

Notes:

Recommended Operating Conditions (Note 9)

Symbol	Pa	arameter	Min	Max	Unit	
Vcc	V _{CC} Operating Voltage	Operating	1.65	5.5	V	
VCC	Operating voltage	Data Retention Only	1.5	_	v	
Vı	Input Voltage		0	5.5	V	
Vo	Output Voltage Active Mode		0	Vcc	٧	
VO	Output Voltage Power-Down Mode		0	5.5	V	
	I _{OH} High-Level Output Current	V _{CC} = 1.65V	_	-4		
		Vcc = 2.3V	_	-8	mA	
lau		Vcc = 2.7V	_	-12		
IOH	Tright-Level Output Outrent	Vcc = 3.0V	_	-16		
			_	-24		
		Vcc = 4.5V	_	-32		
		Vcc = 1.65V	_	4		
		Vcc = 2.3V	_	8		
lou	Low-Level Output Current	Vcc = 2.7V	_	12	mA	
IOL	Low-Level Output Current	Voc. 2.0V	_	16	mA	
		Vcc = 3.0V	_	24		
		Vcc = 4.5V	_	32		
A+/A\/	Input Transition Disc or Fall Date	V _{CC} = 1.65V to 2.7V	_	20	22/1/	
Δt/ΔV	Input Transition Rise or Fall Rate	V _{CC} = 2.7V to 5.5V	_	10	ns/V	
TA	Operating Free-Air Temperature		-40	+125	°C	

Note:

9. Unused inputs should be held at V_{CC} or Ground.

Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
 Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.



Electrical Characteristics (All typical values are at T_A = +25°C.)

			.,	-40°C to +85°C			-40°C to	l lmi4	
Symbol	Parameter	Test Conditions	Vcc	Min	Тур	Max	Min	Max	Unit
			$V_{CC} = 1.65V \text{ to } 1.95V$	0.65 × V _{CC}	_	_	0.65 × V _{CC}	_	
.,	High-Level Input Voltage		V _{CC} = 2.3V to 2.7V	1.7	_	_	1.7	_	.,
V _{IH}		_	V _{CC} = 2.7V to 3.6V	2.0	_	_	2.0	_	V
			V _{CC} = 4.5V to 5.5V	$0.7 \times V_{CC}$	_	_	0.7 × V _{CC}	_	
			V _{CC} = 1.65V to 1.95V	_	_	$0.35 \times V_{CC}$	_	$0.35 \times V_{CC}$	
M	Low-Level		V _{CC} = 2.3V to 2.7V	_	_	0.7	_	0.7	
V _{IL}	Input Voltage	_	V _{CC} = 2.7V to 3.6V	_	_	0.8	_	0.8	V
			V _{CC} = 4.5V to 5.5V	_	_	$0.3 \times V_{CC}$	_	$0.3 \times V_{CC}$	
		I _{OH} = -100μA	1.65V to 5.5V	V _{CC} - 0.1	Vcc	_	V _{CC} - 0.1	_	
		I _{OH} = -4mA	1.65V	1.2	1.53	_	0.95	_	
	High-Level	I _{OH} = -8mA	2.3V	1.9	2.13	_	1.7	_	
Vон	Output	Iон = -12mA	2.7V	2.2	2.5	_	1.9	_	V
	Voltage	I _{OH} = -16mA	01/	2.4	2.7	_	2.2	_	
		Iон = -24mA	3V	2.3	2.6	_	2.0	_	
		I _{OH} = -32mA	4.5V	3.8	4.1	_	3.4	_	
	loı	I _{OL} = 100μA	1.65V to 5.5V	_	0	0.1	_	0.1	
		I _{OL} = 4mA	1.65V	_	0.08	0.45	_	0.7	
	Low-Level	IoL = 8mA	2.3V	_	0.14	0.3	_	0.45	
V _{OL}	Output	I _{OL} = 12mA	2.7V	_	0.19	0.4	1	0.6	V
	Voltage	IoL = 16mA	0)/	_	0.25	0.4	_	0.6	
		I _{OL} = 24mA	3V	_	0.37	0.55	_	0.8	
		I _{OL} = 32mA	4.5V	_	0.43	0.55	_	0.8	
lı	Input Current	Vı = 5.5V or GND	0V to 5.5V	_	± 0.1	±5	_	± 20	μA
loz	Z-State Leakage Current	VI = VIH or VIL VO = 5.5V or GND	3.6V	_	± 0.1	± 10	_	±20	μΑ
loff	Power Down Leakage Current	V _I or V _O = 5.5V	0V	_	± 0.1	±10	_	±20	μΑ
Icc	Supply Current	V _I = 5.5V or GND I _O = 0A	1.65V to 5.5V	_	0.1	10	_	40	μΑ
ΔΙ _{CC}	Additional Supply Current	One input at $V_{CC} - 0.6V$ Other inputs at V_{CC} or GND	2.3V to 5.5V	_	5	500	-	5,000	μΑ
Сі	Input Capacitance	VI = VCC or GND	3.3V	_	2.5	_	_	_	pF



Operating Characteristics

	Parameter	Test Conditions	Vcc = 1.8V Typ	Vcc = 2.5V Typ	Vcc = 3.3V Typ	Vcc = 5V Typ	Unit
0	Power Dissipation	f = 10MHz output enabled	17	17	17	17	pF
C _{pd}	Capacitance	f = 10MHz output disabled	5	5	5	5	pF

Package Characteristics

Symbol	Parameter	Package	Test Conditions	Min	Тур	Max	Unit
		X2-DFN2010-8		_	313	_	
θја	Thermal Resistance Junction- to-Ambient	X2-DFN1410-8	(Note 10)	_	321	_	°C/W
	to-Ambient	X2-DFN1210-8		_	395	_	
	Thermal Resistance Junction- X2-DFN2010-8 X2-DFN1410-8 (Note 10)		_	145	_		
θЈС		X2-DFN1410-8	(Note 10)	_	166	_	°C/W
to-0	to-Case	X2-DFN1210-8		_	236	_	

Note: 10. Test condition for each package type: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

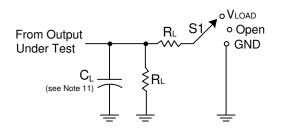
Switching Characteristics

Typical Values at $T_A = +25$ °C and nominal voltages 1.8V, 2.5V, 2.7V, 3.3V, and 5.0V. See Figure 1.

Downstan	From	То	Voc	T _A =	: -40°C to +8	85°C	T _A = -40°C	to +125°C	l lmia	
Parameter	Input	Output	Vcc	Min	Тур	Max	Min	Max	Unit	
			1.8V ± 0.15V	1.0	3.9	9.8	1.0	12.3		
			2.5V ± 0.2V	0.5	2.6	4.9	0.5	6.3		
t _{pd}	Α	Υ	2.7V	1.0	2.8	4.7	1.0	5.9	ns	
			$3.3V \pm 0.3V$	0.5	2.4	4.4	0.5	5.4		
			5.0V ± 0.5V	0.5	1.9	3.9	0.5	4.0		
	OE		1.8V ± 0.15V	1.0	4.1	10.0	1.0	12.5		
			2.5V ± 0.2V	1.0	2.6	5.0	1.0	6.3		
t _{en}		Υ	2.7V	1.0	2.8	4.7	1.0	5.9	ns	
			$3.3V \pm 0.3V$	1.0	2.4	4.1	1.0	5.1		
			5.0V ± 0.5V	0.5	1.8	3.4	0.5	3.9		
			1.8V ± 0.15V	1.0	3.3	12.6	1.0	15.4		
			2.5V ± 0.2V	0.5	1.9	5.7	0.5	7.5		
t _{dis}	dis OE	OE	Υ	2.7V	1.5	3.0	4.8	1.5	6.2	ns
			$3.3V \pm 0.3V$	1.0	2.5	4.4	1.0	5.7		
			5.0V ± 0.5V	0.5	1.8	3.3	0.5	4.4		

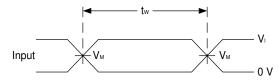


Parameter Measurement Information

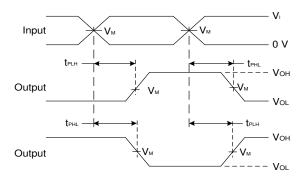


TEST (Notes 14, 15, 16)	S1
tplh/tphl	Open
tplz/tpzl	Vload
tpHz/tpzH	GND

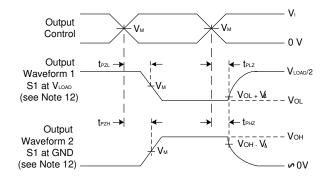
v	Inp	outs	.,	.,		Б	
Vcc	Vı	t _R /t _F	VM VLOAD		CL	R∟	V Δ
1.8V±0.15V	Vcc	≤2ns	Vcc/2	2 × Vcc	30pF	1kΩ	0.15V
2.5V±0.2V	Vcc	≤2ns	Vcc/2	2 × Vcc	30pF	500Ω	0.15V
2.7V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
3.3V±0.3V	3V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
5V±0.5V	Vcc	≤2.5ns	Vcc/2	2 × Vcc	50pF	500Ω	0.3V



Voltage Waveform Pulse Duration (Note 13)



Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs (Note 13)



Voltage Waveform Enable and Disable Times Low and High Level Enabling

Figure 1. Load Circuit and Voltage Waveforms

Notes:

- 11. Includes test lead and test apparatus capacitance.
 12. All pulses are supplied at pulse repetition rate ≤ 10MHz.
 13. Inputs are measured separately one transition per measurement.
- 14. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- 15. t_{PZL} and t_{PZH} are the same as t_{en}.
- 16. t_{PLH} and t_{PHL} are the same as $t_{pd.}$



Marking Information

(Top View)

<u>XX</u>

XX : Identification Code
Y : Year : 0~9
W : Week : A~Z : 1~26 week;
a~z : 27~52 week; z represents
52 and 53 week

X: Internal Code

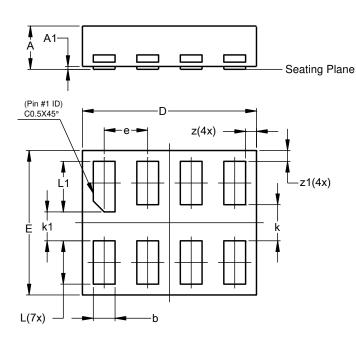
Part Number	Package	Identification Code
74LVC2G126HD4-7	X2-DFN2010-8	9X
74LVC2G126HK3-7	X2-DFN1410-8	9Y
74LVC2G126RA3-7	X2-DFN1210-8	9Z



X2-DFN1210-8 Package Outline Dimensions

 $Please \ see \ http://www.diodes.com/package-outlines.html \ for \ the \ latest \ version.$

X2-DFN1210-8

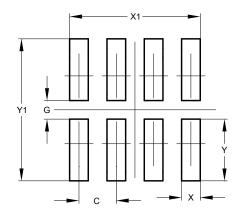


X2-DFN1210-8			
Dim	Min	Max	Тур
Α	-	0.35	0.30
A 1	0	0.03	0.02
b	0.10	0.20	0.15
D	1.15	1.25	1.20
Е	0.95	1.05	1.00
е	1	-	0.30
k	-	-	0.25
k1	-	-	0.20
L	0.25	0.35	0.30
L1	0.30	0.40	0.35
Z	0.050	0.100	0.075
z1	0.050	0.100	0.075
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1210-8



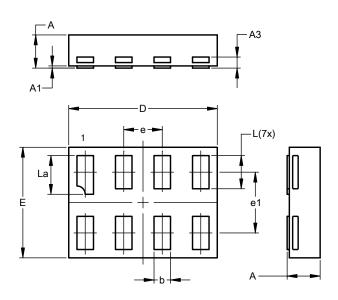
Dimensions	Value (in mm)	
С	0.300	
G	0.150	
Х	0.150	
X1	1.050	
Υ	0.500	
Y1	1.150	



X2-DFN1410-8 Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1410-8

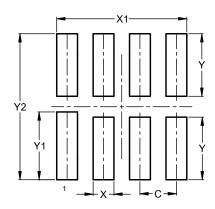


X2-DFN1410-8			
Dim	Min	Max	Тур
Α	0.30	0.35	0.33
A 1	0.00	0.03	0.02
A3			0.10
b	0.12	0.20	0.15
D	1.30	1.40	1.35
E	0.95	1.05	1.00
е	-		0.35
e1	-		0.55
L	0.27	0.35	0.30
L1	0.32	0.40	0.35
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1410-8



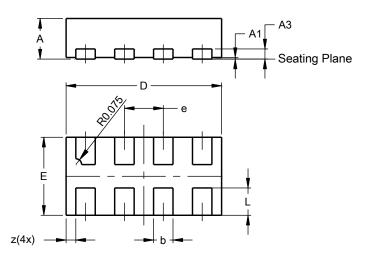
Dimensions	Value	
פווטופוופווט	(in mm)	
С	0.350	
Х	0.200	
X1	1.250	
Y	0.600	
Y1	0.650	
Υ2	1 400	



X2-DFN2010-8 Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN2010-8

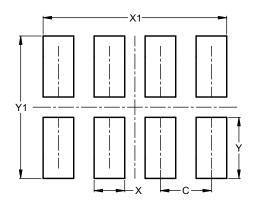


X2-DFN2010-8			
Dim	Min	Max	Тур
Α		0.40	
A1	0.00	0.05	0.02
A3	1	1	0.13
b	0.20	0.30	0.25
D	1.950	2.05	2.00
Е	0.95	1.05	1.00
е			0.50
L	0.30	0.40	0.35
Z			0.125
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN2010-8



Dimensions	Value (in mm)
С	0.500
Х	0.300
X1	1.800
Υ	0.600
V1	1 400



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